

[NAME OF DOCUMENT]

## ABSTRACT

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[OBJECT]

An object is to provide a semiconductor device and a method for manufacturing the same that is excellent in reduction of leak current caused by the short-channel effect.

[MEANS FOR SOLUTION]

A field effect transistor formed on a SOI substrate is equipped with a gate (102) formed on a substrate, a source (103) and a drain (104) each spaced a specified distance from a crystal region below the gate, a first extension region (110) that extends in a channel formed between the source and an area below the gate, and a second extension region (111) that extends in a channel formed between the drain and an area below the gate, wherein junction depths ( $X_s$ ,  $X_d$ ) of the first and second extension regions is formed shallower than junction depths ( $X_t$ ) of the source region (103) and the drain region (104).

[SELECTED FIGURE] Fig. 1